

CLAIMS

What is claimed is:

1. A method of manufacturing a wiring board, comprising:

performing a plating process on a land in a condition that a resist film having an opening exposing at least a center of the land is formed on a substrate with a wire having the land formed thereon so that a first portion of an edge of the opening is disposed on the substrate and a second portion of the edge is disposed on the land.

2. A method of manufacturing a wiring board, comprising

forming a resist film on a substrate with a wire having a land having a shape including a depression formed thereon, the resist film having an opening exposing at least a center of the land, so that, taking a smallest circumscribing rectangle of the land as a reference, every side of the rectangle is covered by the resist film while the depression of the land is partially exposed through the opening.

3. A method of manufacturing a wiring board, comprising:

forming a resist film on a substrate with a wire having a land formed thereon, the resist film having an opening exposing a part of a periphery and a center of the land, so that a sum of a length of a first side of the land which is covered by the resist film is larger than a sum of a second side which is exposed through the opening.

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4. The method of manufacturing a wiring board according to Claim 1,

wherein the land has a shape including a depression, and the resist film is formed so that the depression is partially exposed through the opening.

5. The method of manufacturing a wiring board according to Claim 2, further comprising:

performing a plating process on the land with the resist film formed.

6. A wiring board manufactured by the method according to Claim 1.

7. A wiring board, comprising:

a substrate;

a wire formed on the substrate and having a land having a shape including a depression; and

a resist film having an opening and covering the wire so that a part of a periphery and a center of the land are exposed via the opening,

wherein, taking a smallest circumscribing rectangle of the land as a reference, the resist film is formed so that every side of the rectangle is covered by the resist film while the depression of the land is partially exposed through the opening.

8. A wiring board, comprising:

a substrate;
a wire formed on the substrate and having a land; and
a resist film having an opening and covering the wire so that a part of a periphery and a center of the land are exposed via the opening,
wherein the resist film is formed so that a sum of a length of a first side of the land which is covered by the resist film is larger than a sum of a second side which is exposed through the opening.

9. The wiring board according to Claim 8,
wherein the land has a shape including a depression, and the depression is partially exposed through the opening.

10. A semiconductor device, comprising:
the wiring board according to Claim 6.

11. An electronic module, comprising:
the semiconductor device according to Claim 10.

12. An electronic apparatus, comprising:
the electronic module according to Claim 11.

13. The method of manufacturing a wiring board according to Claim
2,
wherein the land has a shape including a depression, and the resist film

is formed so that the depression is partially exposed through the opening.

14. The method of manufacturing a wiring board according to Claim 3, further comprising:

performing a plating process on the land with the resist film formed.

15. A wiring board manufactured by the method according to Claim 2.

16. A wiring board manufactured by the method according to Claim 3.

17. A semiconductor device, comprising:
the wiring board according to Claim 7.

18. An electronic module, comprising:
the semiconductor device according to Claim 17.

19. A semiconductor device, comprising:
the wiring board according to Claim 8.

20. An electronic module, comprising:
the semiconductor device according to Claim 19.

21. The method of manufacturing a wiring board according to Claim 3,

wherein the land has a shape including a depression, and the resist film is formed so that the depression is partially exposed through the opening.